



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260331002.1
Qualifying a Design change, Fab process and FMX as an
additional Assembly site option for select devices
Change Notification / Sample Request

Date: March 31, 2026
To: BAE Systems PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260331002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CD74HC14M96	NULL
SN74HC04N	NULL
SN74HC14N	NULL
SN74HC14DRG4	NULL
CD74HC14E	NULL
SN74HC7001DR	NULL
CD74HC4075NSR	NULL
CD74HC132E	NULL
SN74HC02N	NULL
CD74HC00M96	NULL
CD74HC02E	NULL
SN74HC00DR	NULL
SN74HC08DRG4	NULL
SN74HC04DR	NULL
SN74HC14DR	NULL
CD74HC4075NSR	WBAL2538715-002
SN74HC10DR	NULL
SN74HC14PWR	NULL
SN74HC08PWR	NULL
SN74HC08DR	NULL
SN74HC05DR	NULL
CD74HC00E	NULL
CD74HC132M96	NULL
SN74HC132N	NULL
CD74HC4075M96	NULL
SN74HC04PWR	NULL
SN74HC00NE4	NULL
SN74HC08N	NULL
SN74HC10N	NULL
SN74HC00N	NULL
SN74HC08PWRG4	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260331002.1		PCN Date:	March 31, 2026																									
Title:	Qualifying a Design change, Fab process and FMX as an additional Assembly site option for select devices																												
Customer Contact:	Change Management team		Dept:	Quality Services																									
Proposed 1st Ship Date:	June 29, 2026		Sample requests accepted until:	May 30, 2026*																									
*Sample requests received after May 30, 2026 will not be supported.																													
Change Type:																													
☒ Assembly Site	☒ Design	☐ Wafer Bump Material																											
☐ Assembly Process	☐ Data Sheet	☐ Wafer Bump Process																											
☐ Assembly Materials	☐ Part number change	☐ Wafer Fab Site																											
☐ Mechanical Specification	☐ Test Site	☐ Wafer Fab Material																											
☒ Packing/Shipping/Labeling	☐ Test Process	☒ Wafer Fab Process																											
PCN Details																													
Description of Change:																													
Texas Instruments is pleased to announce a die design and fab process update for improved manufacturing efficiency & Qualify FMX as additional Assembly site options for the select devices listed below. <table border="1"> <thead> <tr> <th colspan="3">Current</th> <th colspan="3">Proposed</th> </tr> <tr> <th>Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Fab site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>RFAB</td> <td>LBC9</td> <td>300mm</td> <td>RFAB</td> <td>LBC9 PLV</td> <td>300mm</td> </tr> </tbody> </table> The die revision was also changed as a result of the process change. Group 1 device (Design only): Device remains at existing Assembly site Group 2 device (Design, Assembly site) <table border="1"> <thead> <tr> <th></th> <th>Current site</th> <th>Additional Site</th> </tr> </thead> <tbody> <tr> <td>Assembly site</td> <td>MLA</td> <td>FMX</td> </tr> </tbody> </table> *No material differences between sites Qual details are provided in the Qual Data Section.						Current			Proposed			Fab Site	Process	Wafer Diameter	Fab site	Process	Wafer Diameter	RFAB	LBC9	300mm	RFAB	LBC9 PLV	300mm		Current site	Additional Site	Assembly site	MLA	FMX
Current			Proposed																										
Fab Site	Process	Wafer Diameter	Fab site	Process	Wafer Diameter																								
RFAB	LBC9	300mm	RFAB	LBC9 PLV	300mm																								
	Current site	Additional Site																											
Assembly site	MLA	FMX																											
Reason for Change:																													
Improve Manufacturing Efficiency																													
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																													
Review the SDP for full evaluation of the change based on the customer use case.																													
Impact on Environmental Ratings																													
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																													

RoHS	REACH	Green Status	IEC 62474												
☒ No Change	☒ No Change	☒ No Change	☒ No Change												
Changes to product identification resulting from this PCN:															
Die Rev: Current New Die Rev [2P] Die Rev [2P] <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; text-align: center; color: blue;">B</td> <td style="width: 50%; text-align: center; color: blue;">A</td> </tr> </table>				B	A										
B	A														
Assembly Site Information: <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 25%;">Assembly Site</th> <th style="width: 25%;">Assembly Site Origin (22L)</th> <th style="width: 25%;">Assembly Country Code (23L)</th> <th style="width: 25%;">Assembly City</th> </tr> </thead> <tbody> <tr> <td>TI Malaysia</td> <td>MLA</td> <td>MYS</td> <td>Kuala Lumpur</td> </tr> <tr> <td style="color: blue;">TI Mexico</td> <td style="color: blue;">MEX</td> <td style="color: blue;">MEX</td> <td style="color: blue;">Aguascalientes</td> </tr> </tbody> </table>				Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	TI Malaysia	MLA	MYS	Kuala Lumpur	TI Mexico	MEX	MEX	Aguascalientes
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City												
TI Malaysia	MLA	MYS	Kuala Lumpur												
TI Mexico	MEX	MEX	Aguascalientes												
Sample product shipping label (not actual product label)  MADE IN: Malaysia 2DC: 20: <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: 39 LBL: 5A (L)T0:1750  (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: V 0033317 (20L) CS0: SHE (21L) CC0: USA (22L) AS0: MLA (23L) AC0: MYS				MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04								
MSL 2 / 260C / 1 YEAR	SEAL DT														
MSL 1 / 235C / UNLIM	03/29/04														
Group 1 Product Affected: (Design only)															

CD74HC00E	SN74HC02DRG4	SN74HC08NSR
CD74HC00EE4	SN74HC02N	SN74HC08PWR
CD74HC02E	SN74HC02NE4	SN74HC08PWRG4
CD74HC04E	SN74HC02NSR	SN74HC10N
CD74HC04M96	SN74HC02NSRG4	SN74HC10NE4
CD74HC08PWRG4	SN74HC02PWR	SN74HC10NSR
CD74HC132E	SN74HC02PWRG4	SN74HC10NSRG4
CD74HC132EE4	SN74HC04DR	SN74HC10PWRG4
CD74HC14E	SN74HC04DRG4	SN74HC132DR
CD74HC14EE4	SN74HC04N	SN74HC132N
CD74HC14M96	SN74HC04NE4	SN74HC132NE4
CD74HC14PWRG4	SN74HC04NSR	SN74HC132NSR
CD74HC4075NSR	SN74HC04NSRG4	SN74HC132NSRG4
CD74HC4075PWRG4	SN74HC04PWR	SN74HC132PWR1G4
SN74HC00ANSR	SN74HC04PWRG4	SN74HC14ANSR
SN74HC00APWR	SN74HC05DRG4	SN74HC14DBR
SN74HC00DR	SN74HC05NSR	SN74HC14DR
SN74HC00DRG4	SN74HC05NSRE4	SN74HC14DRG4
SN74HC00N	SN74HC05PWR	SN74HC14N
SN74HC00NE4	SN74HC05PWRG4	SN74HC14NE4
SN74HC00NSR	SN74HC08ANSR	SN74HC14NSR
SN74HC00PWR	SN74HC08DR	SN74HC14NSRE4
SN74HC00PWRG4	SN74HC08DRG4	SN74HC14PWR
SN74HC02ANSR	SN74HC08N	SN74HC14PWRG4
SN74HC02DR	SN74HC08NE4	

Group 2 Product Affected: (Design, Assembly site)

CD74HC00M96	CD74HC10M96	SN74HC10DR
CD74HC00M96G4	CD74HC132M96	SN74HC10DRG4
CD74HC02M96	CD74HC132M96G4	SN74HC132DR1G4
CD74HC02M961G4	CD74HC14M961G4	SN74HC7001DR
CD74HC04M96G4	CD74HC4075M96	SN74HC7001DRG4
CD74HC08M96	CD74HC4075M96G4	
CD74HC08M961G4	SN74HC05DR	

Group 1 Qualification Report

BD123 14 PIN N

Approve Date 13-MARCH -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HC14N	QBS Process Reference: SN74HCS74QPWRQ1	QBS Package Reference: SN74HC00N	QBS Package Reference: SN74HC04N	QBS Package Reference: SN74HC164N	QBS Package Reference: NE556N	QBS Product Reference: SN74HC14QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	1/77/0	1/77/0	1/77/0	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	1/77/0	-	-	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	-	-	-	1/45/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	-	-	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder,	-	1/22/0	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-	-	1/10/0
ESD	E2	ESD CDM	-	2000 Volts	-	-	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	750 Volts	1/3/0	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	-	-	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-	-	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HC14N is qualified at NOT CLASSIFIED 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-111

Qualification Report
BD123 14 PIN D
Approve Date 17-March-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HC08DR	Qual Device: SN74HC14DR	Qual Device: SN74HCS14DR	Qual Device: SN74HCS266DR	QBS Process Reference: SN74HCS74QWQRQ1	QBS Package Reference: SN74LVC11ADRQ1	QBS Package Reference: SN74LVC132ADRQ1	QBS Package Reference: SN74LVC74ADRQ1	QBS Product Reference: SN74HC05DR	QBS Product Reference: SN74HC08PWR	QBS Product Reference: SN74HC14PWR	QBS Product Reference: SN74HCS14PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
TC	A4	Temperature Cycle	-55C/150C	500 Cycles	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	1/45/0	1/45/0	1/45/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	-	-	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	1/15/0	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpl>1.67	-	-	-	-	-	3/30/0	1/10/0	1/10/0	1/10/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0	-	-	-	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	1/6/0	1/3/0	-	-	-	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-	-	-	1/30	1/30/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpl>1.67 Room, hot, and cold	-	-	-	-	-	3/60/0	2/60/0	1/30/0	1/30/0	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HC08DR is qualified at MSL1 260C

Qual Device SN74HC14DR is qualified at MSL1 260C

Qual Device SN74HCS14DR is qualified at MSL1 260C

Qual Device SN74HCS266DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2601-070

Qualification Report
BD123 14 PIN NS
Approve Date 13-March-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HC14NSR	QBS Process Reference: SN74HCS74QFWRQ1	QBS Package Reference: SN74LVC8T245NSR	QBS Package Reference: TXS0108EQDGSRQ1	QBS Package Reference: SN74AC3G98DGSRQ1	QBS Package Reference: TPLD1201DGSRQ1	QBS Product Reference: SN74HC14QFWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	1/77/0	1/77/0	1/77/0
UHA	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	1/77/0	1/77/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	1/45/0	1/45/0	-	1/45/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	1/77/0	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder,	-	1/22/0	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	1/10/0	1/10/0	1/10/0	1/10/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD CDM	-	750 Volts	1/3/0	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	1/3/0	-	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	-	-	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	1/30/0	1/30/0	3/90/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HC14NSR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-112

Qualification Report BD123 14 PIN DB Approve Date 13-March-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HC14DBR	QBS Process Reference: SN74HC574QFWRQ1	QBS Package Reference: TLC320AD77CDBR	QBS Package Reference: PCM1794AQDBRQ1	QBS Product Reference: SN74HC14NSR	QBS Product Reference: SN74HC14QFWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	-	-	1/45/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	3/231/0	-	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	1/22/0	-	-	-	1/22/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	3/30/0	-	1/10/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	750 Volts	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	1/3/0	-	1/3/0	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	-	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	3/90/0	-	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HC14DBR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-109

Qualification Report BD123 14 PIN PW Approve Date 13-March-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HCS11PWR	Qual Device: SN74HC14PWR	Qual Device: SN74HCS14PWR	Qual Device: SN74HCS4075PWR	QBS Package, Process Reference: SN74HCS74QPWRQ1	QBS Product Reference: SN74HC14QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	1/10/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	750 Volts	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	1/3/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HCS11PWR is qualified at MSL1 260C

Qual Device SN74HC14PWR is qualified at MSL1 260C

Qual Device SN74HCS14PWR is qualified at MSL1 260C

Qual Device SN74HCS4075PWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2602-017

Group 2 Qualification Report

Approve Date 17-March-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HC08DR	Qual Device: SN74HC14DR	Qual Device: SN74HCS14DR	Qual Device: SN74HCS266DR	QBS Process Reference: SN74HCS74QFWRQ1	QBS Package Reference: SN74LVC11ADRQ1	QBS Package Reference: SN74LVC132ADRQ1	QBS Package Reference: SN74LVC74ADRQ1	QBS Product Reference: SN74HC05DR	QBS Product Reference: SN74HC08PWR	QBS Product Reference: SN74HC14PWR	QBS Product Reference: SN74HCS14PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	1/45/0	1/45/0	1/45/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	-	-	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	1/15/0	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	1/10/0	1/10/0	1/10/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0	-	-	-	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	1/6/0	1/3/0	-	-	-	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-	-	-	1/30	1/30/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0	2/60/0	1/30/0	1/30/0	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HC08DR is qualified at MSL1 260C

Qual Device SN74HC14DR is qualified at MSL1 260C

Qual Device SN74HCS14DR is qualified at MSL1 260C

Qual Device SN74HCS266DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2601-070

Qualification Report

Approve Date 17-March-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74HC05DR	Qual Device: SN74HC10DR	QBS Process Reference: SN74HCS74QPWRQ1	QBS Package Reference: SN74LVC11ADRQ1	QBS Package Reference: SN74LVC132ADRQ1	QBS Package Reference: SN74LVC74ADRQ1	QBS Product Reference: SN74HCS14PWR
HAST	A2	Biased HAST	130C/85%RH	192 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	1/45/0	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/22/0	-	1/15/0	1/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	1/10/0	1/10/0	1/10/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	1/6/0	1/3/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	2/60/0	1/30/0	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74HC05DR is qualified at MSL1 260C

Qual Device SN74HC10DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2602-006

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